

ABSTRACT OF THE DISCLOSURE

A polishing apparatus has a polishing surface, a top ring for holding a semiconductor wafer, and a top ring shaft for pressing the top ring against the polishing surface. The top ring has a retainer ring for holding a
5 peripheral portion of the semiconductor wafer, a housing substantially in a form of a disk which is connected to the top ring shaft, a sliding contact joint interconnecting the retainer ring and the housing in a state such that the retainer ring and the housing are brought into sliding contact with each other.